Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	397	etchant same nozzles same wafers	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/14 08:06
L5	1003	(etchant or slurry) same nozzles same wafers	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/14 08:06
L8	1994	(etchant or slurry) same remov$4 same suction	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/14 08:05
L10	816	5 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/14 08:05
L11	4970	(etchant or slurry or solution) same (nozzles or inlet) same wafers	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/14 08:08
L13	1351	@pd<="19981231" and 11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/14 08:10
L15	34	zahorik-russell-c.in.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/14 08:35
L16	37	hudson-guy-f.in.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/14 08:36
L17	5	dobson-todd-a.in.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/14 08:37
L18	22	gordon-brian-f.in.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/14 08:37